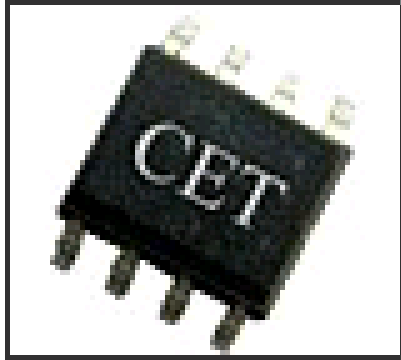


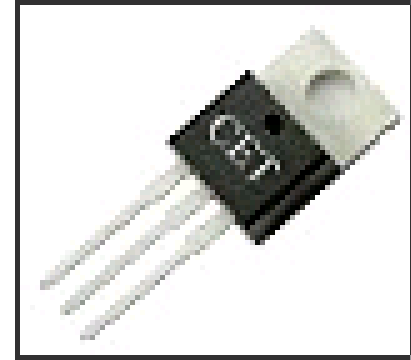
華瑞功率電子股份有限公司

CET-MOS Corp.

Company profile



92, Jian Yi Rd., Chung-Ho Dist.,
New Taipei City, Taiwan, R.O.C.
TEL:886-2-22229138
FAX:886-2-22223833



Agenda



CET-MOS Overview



Application & Advantage



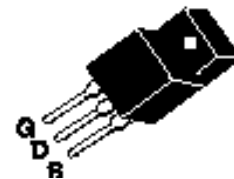
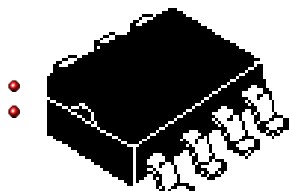
Product Roadmap



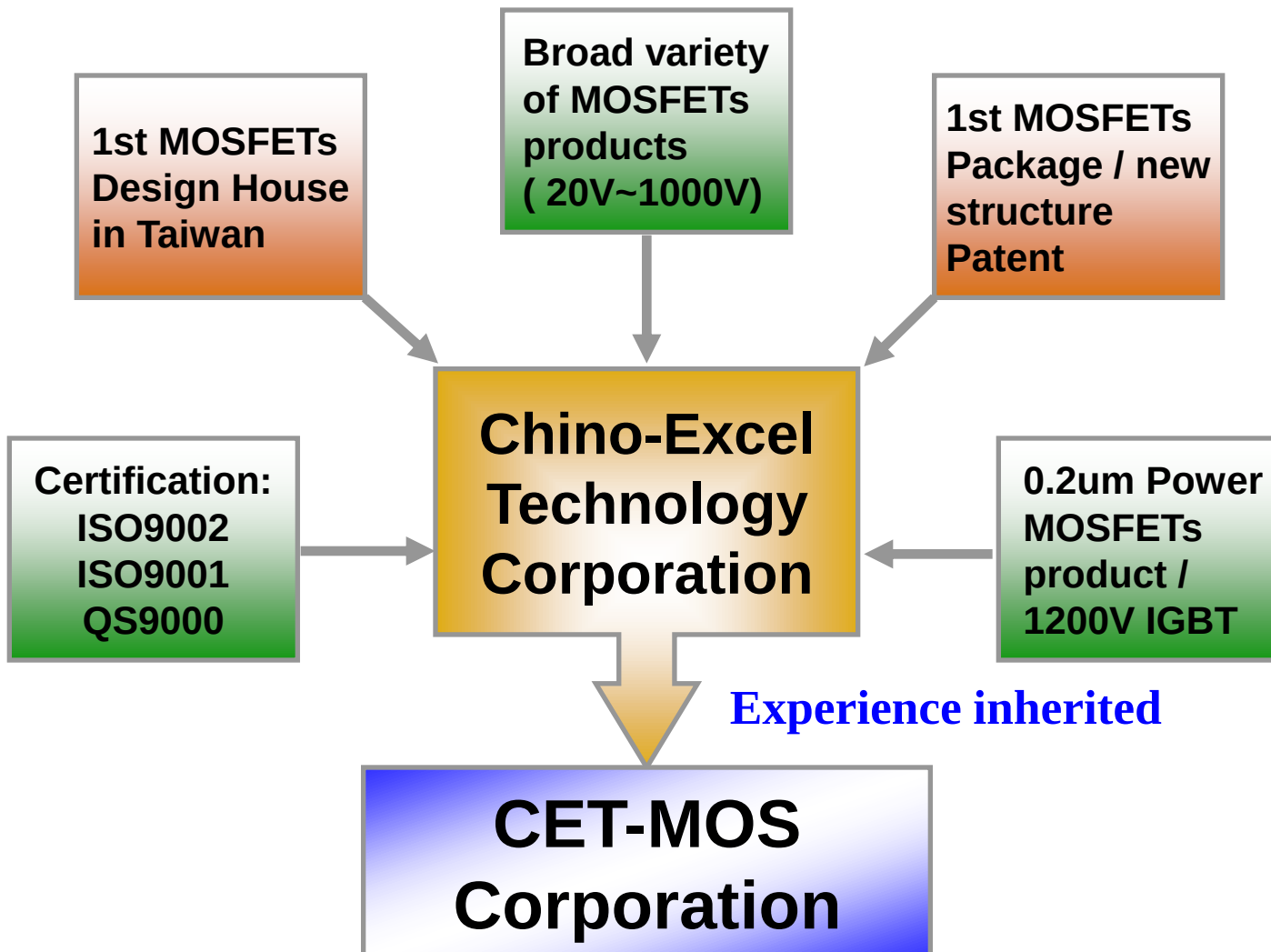
Conclusion

Company Overview

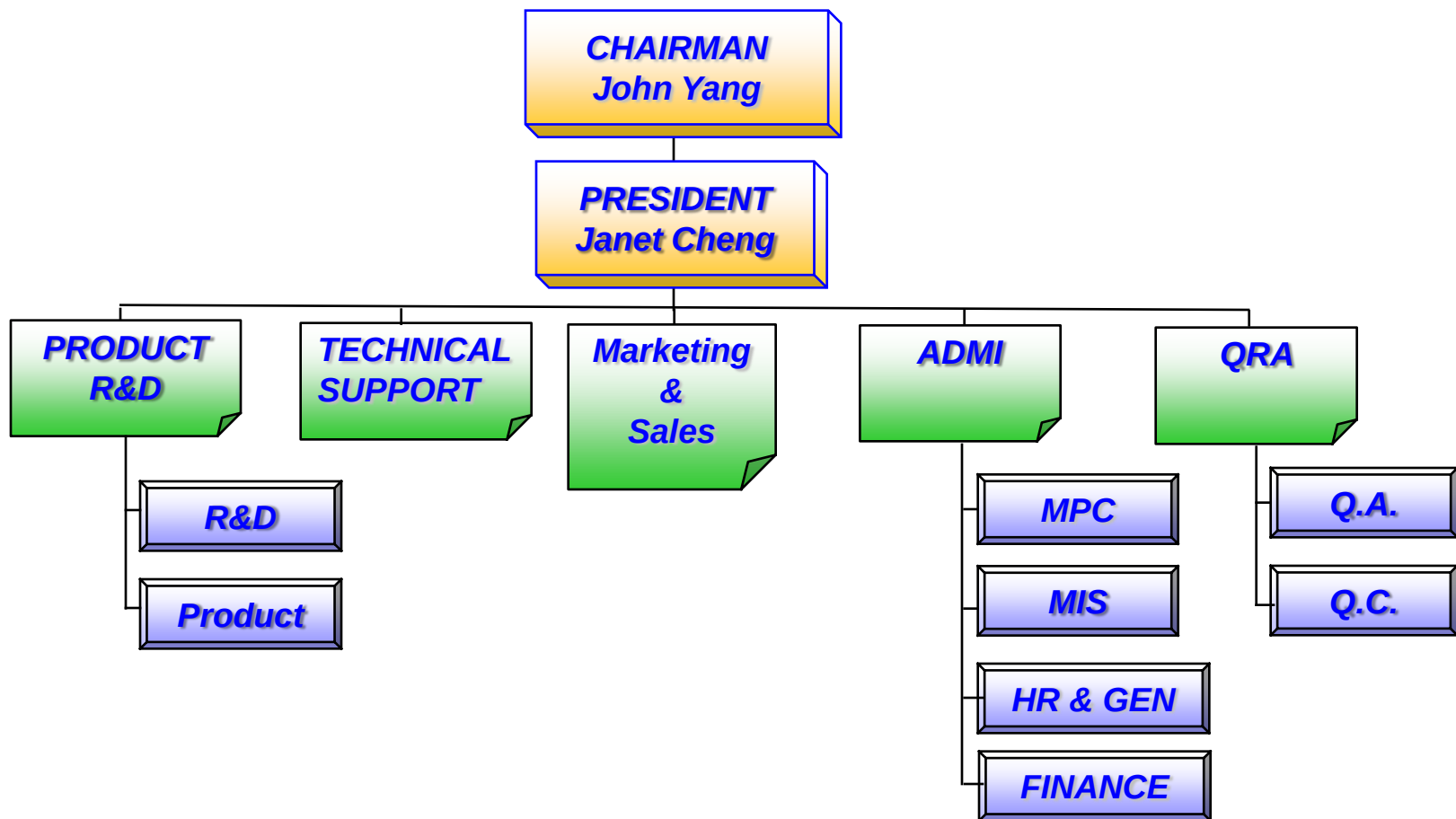
- **EST. DATE :** April, 2012.
- **EMPLOYEES:** 35 People
- **CAPITAL :** USD 33 Million.
- **LOCATION :** Chung-Ho Dist., New Taipei City, Taiwan, R.O.C.
- **SPECIALTIES:**
 - × Own Product Designs
 - × Set Up Wafer Process Abilities
 - × Own Reliability Testing Equipment



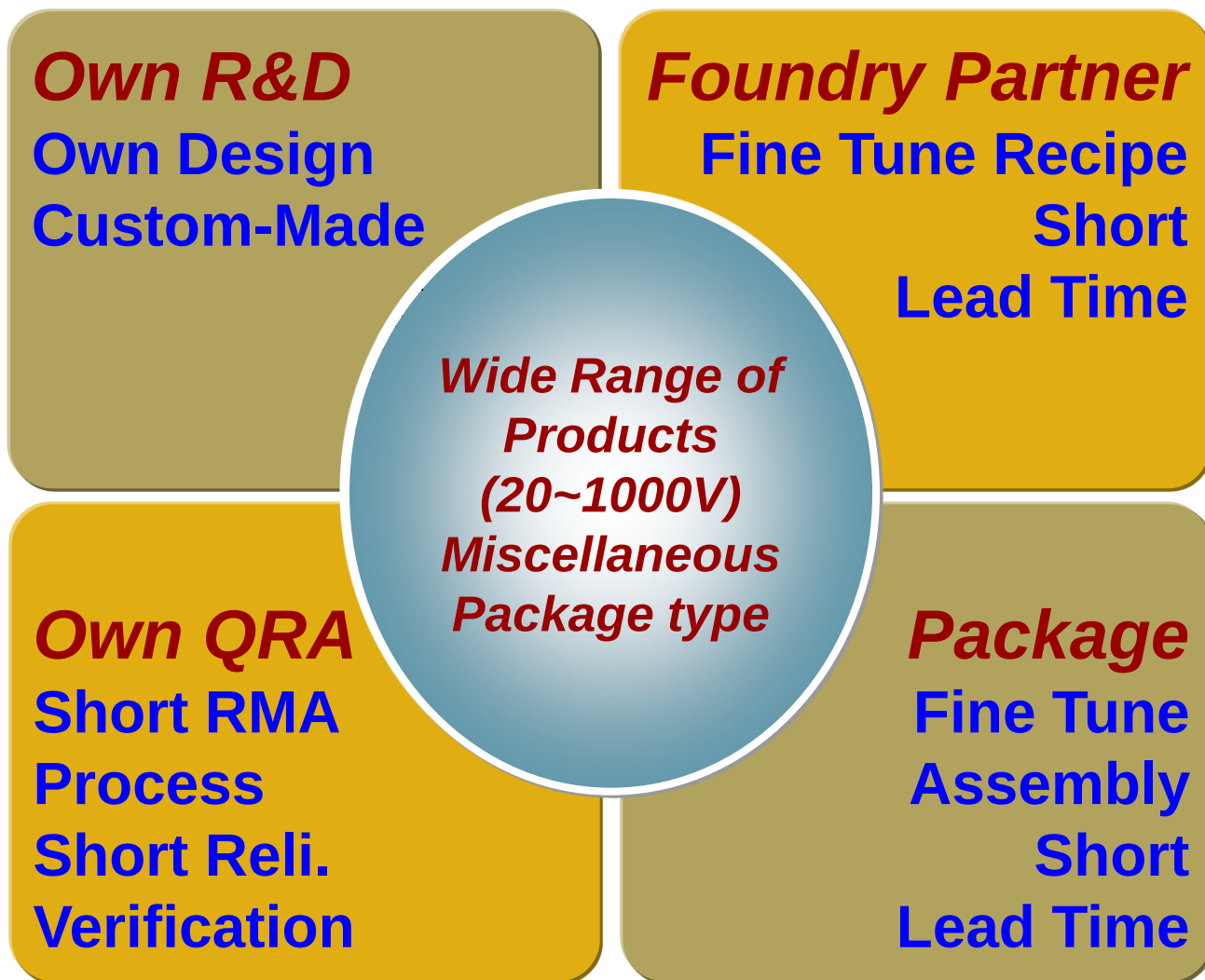
Company Background



CET-MOS Organization



CET-MOS Advantage



Miscellaneous Application



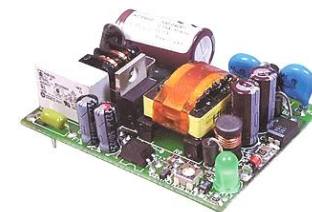
M/B



DC Fan



N/B



SPS



Lin-Ion Battery



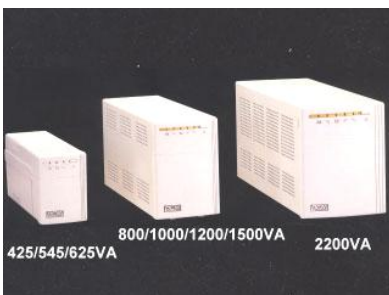
LCD Monitor/TV



Inverter



HID Ballast



UPS



Power-Inverter



Adapter



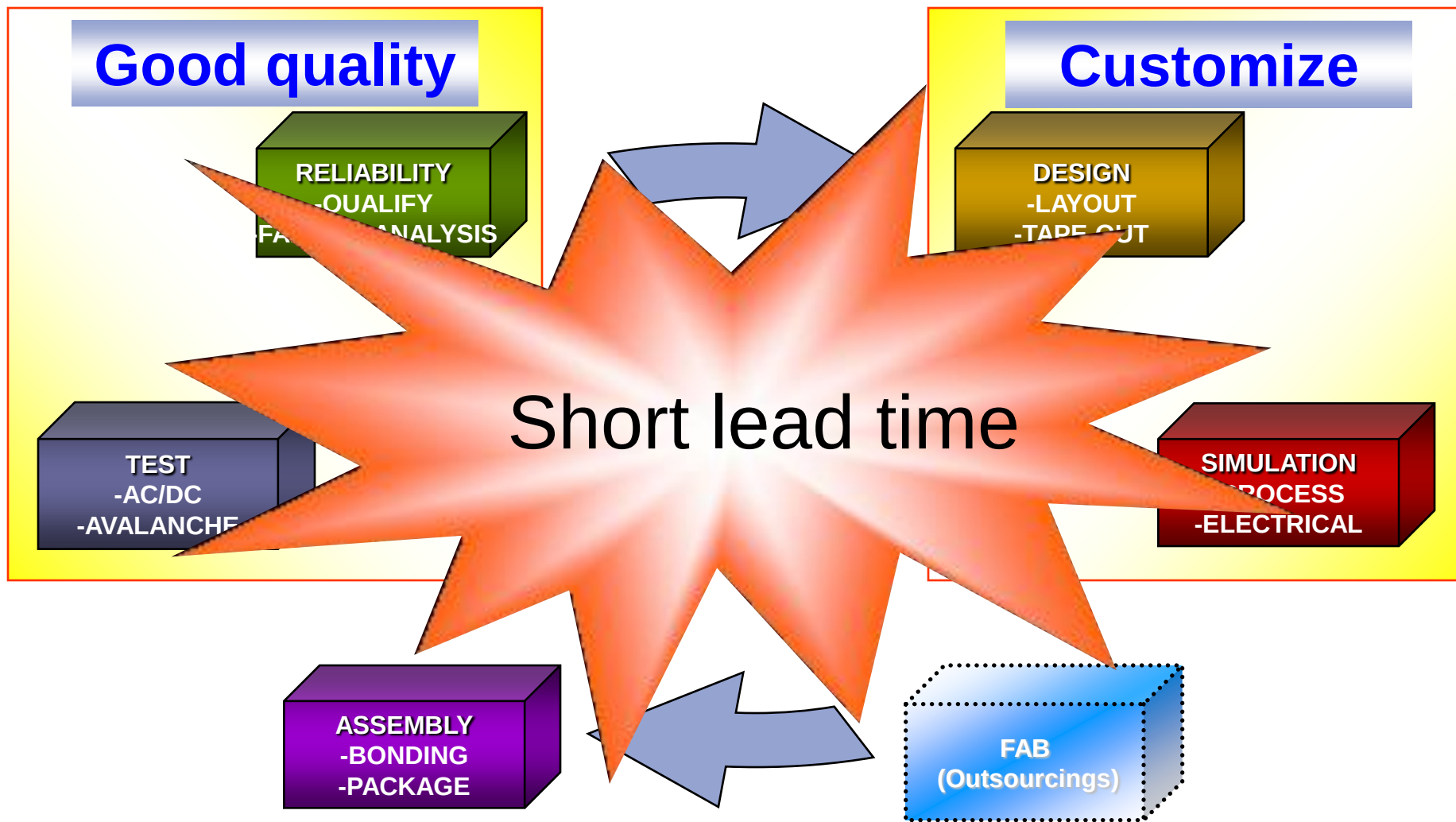
Power Tool

Multiple Package Type

Available Package				2013	2014	2015
- SOP-8 9435A 61S4Z - SOT-23 016B - SOT-223 3055L 61S4Z - SOT-89 3055L 61S4Z	- SOT-26 136B - TO-220F - TO-251 02N6 61S4Z - TO-252 4311 61S4Z	- TO-252-4 4269 61S4Z - TO-247 - TO-263 - CET CEB04N6 61S4Z - TO-3P	- TO-92 - CEK 02N6A 61S4Z - TO-220 - CET CEP02N6 61S4Z - TSSOP-8 8205 61S4ZE - TO-126 02N6 16S4Z	- TO252-4 - DFN3*3 - DFN2*2	- Power Pack 5*6 - Power Pack 3*3	- Power Pack 5*6 E2 - TO-126 - DFN2*5

● CET-MOS can provide variable package.

Design Flow



CET-MOS Capacity

Wafer capacity

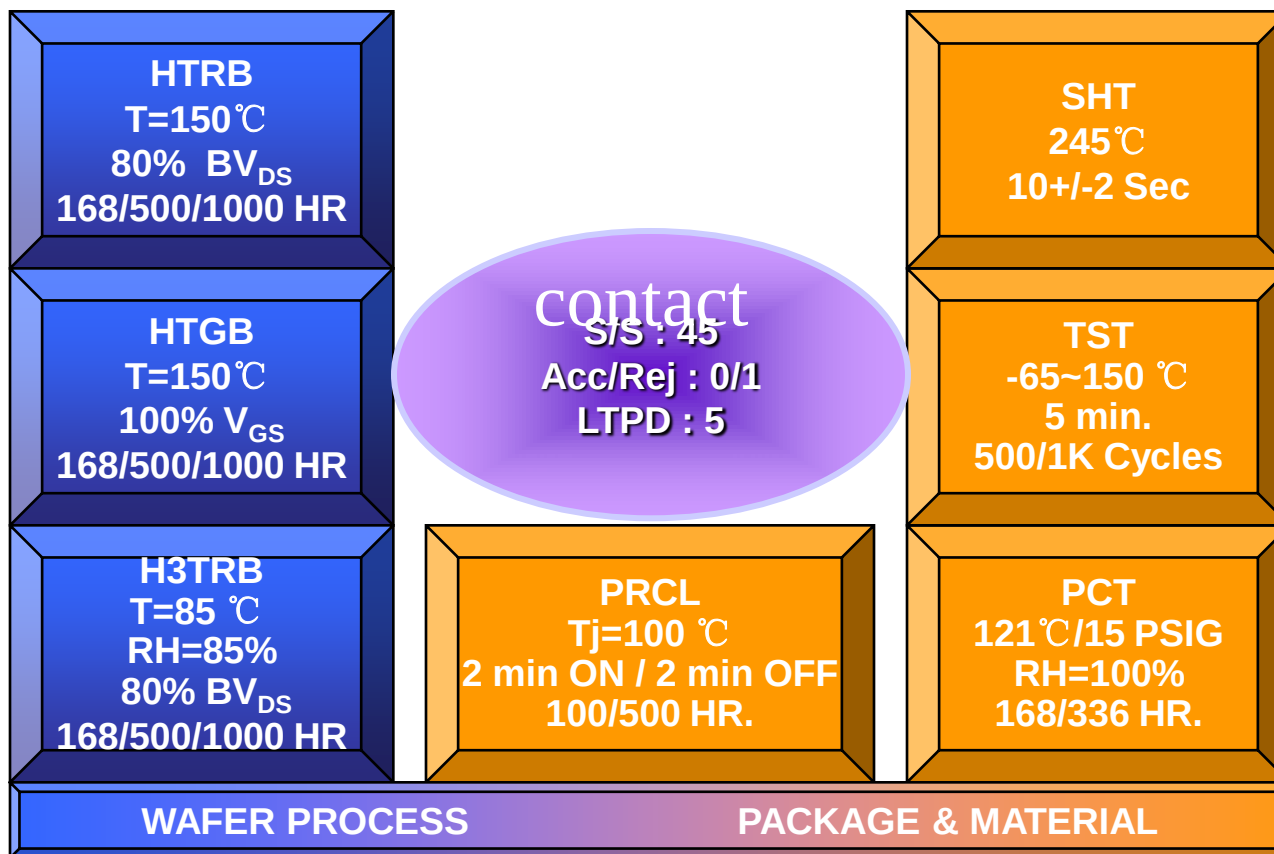
Foundry Wafer Size	6"	6"	8"
Wafer Process	Planar	Trench	Trench
Capacity (pcs/Month)	15K (~23KK dies)	5K (~20KK dies)	10K (~180KK dies)

Package capacity

Package	Taiwan	China	Korea	Malaysia	Total Capacity (K)
SOP8	15,000	40,000		10,000	65,000
TSSOP08		25,000		10,000	35,000
TO-220	8,000	20,000	12,000		40,000
TO-220F		20,000	10,000		30,000
TO-263		10,000	8,000		18,000
TO-251	20,000	20,000	8,000		48,000
TO-252	20,000	20,000	8,000		48,000
TO-247		8,000	5,000		13,000
TO-3P		10,000	6,000		16,000
SOT-23	15,000	50,000			65,000
SOT-223		10,000			10,000
SOT-89		25,000			25,000
TSOP6		20,000			20,000
TO-92		25,000			25,000
DIP8	10,000	15,000		6,000	31,000
SC70(SOT-323)		5,000			5,000
TO-126		5,000			5,000
PR PAK 5*6	5,000	5,000			10,000
TOTAL	88,000	333,000	57,000	26,000	509,000

Reliability Qualification

7 ITEMS RELIABILITY TESTS



Lead Time

Unit : weeks

	Raw Material	Foundry	Assembly		Total L/T
			CET	Subcon	
	8~12	4~6	1~2	6~8	
Best Case	0	0	1	4~6	1~6
Normal Case	4~6	4~6	2	6~8	2~10
Worse Case	6~8	6~8	2	8	8~16
Stock On Hand	0	0	0	0	On-time

Remark: Assembly

by CET : SO8 / DPAK / IPAK / TO220

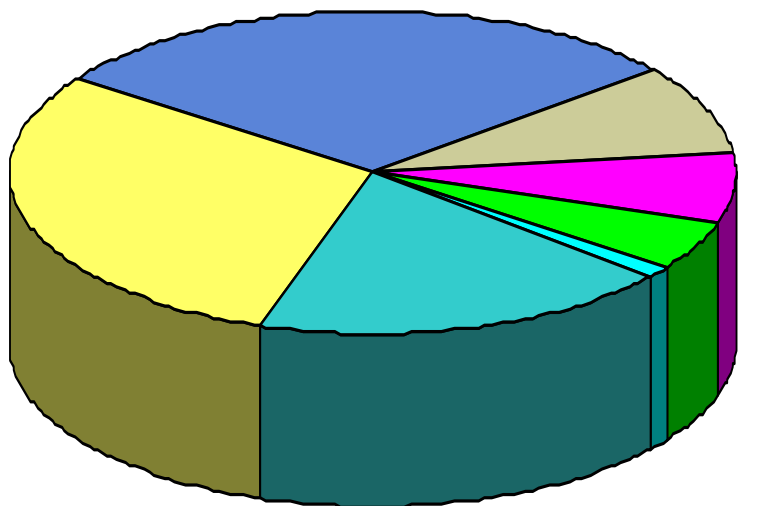
by Subcon: SO8/SOT-23/TO-220 FULL PKG/SOT-89/SOT-223/ DPAK
IPAK/TO220/TO 3P/TO-247/TSOP 6/TSSOP8 /TO92

Technology Roadmap

	CET		CET-MOS
	Available Technology	2011	2012
LOW VOLTAGE	.Low Qgd(Special Oxide) .Ultra-low Rdson (High Density) .High Speed(Special Gate) .8" 650M cell	.High UIS Trench POWERMOS .Low Rg Device .-100V Trench Device .8" 650M Cell	.Ultra fast device .Power PACK Device .Ultra-low Rdson .Custom Specific Design Service
MIDDLE VOLTAGE	- Super Low Rdson .High Switch Speed .Low Gate Charge .100 Trench Power MOS	.High UIS Device .ESD Device .150 Trench Power MOS	.Trench (100V~200V) .-200V Power MOSFET .Custom Specific Design Service
HIGH VOLTAGE	.High Voltage DMOS (UP TO 1000V) .Low Gate Charge .LTO process - High Avalanche Energy	.Ultra-low Rdson .Low Qgd .IGBT (600V~1200V) .High Voltage to1000V	.IGBT (~1500V) .High UIS High Voltage Power MOS(~1500V) .Custom Specific Design Service

Coverage of CET-MOS

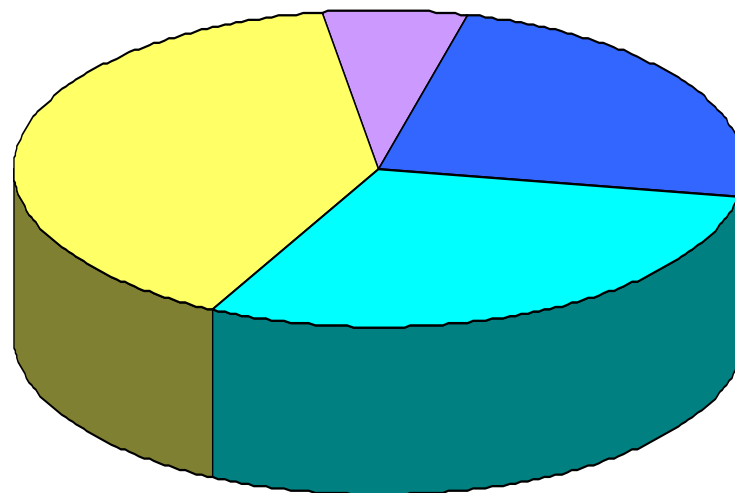
By Application



■ UPS 19%
 ■ SPS 29%
 ■ DC Fan 7%
 ■ Other 1%

■ Consumer 30%
 ■ Power tool 9%
 ■ Battery pack 5%

By Voltage

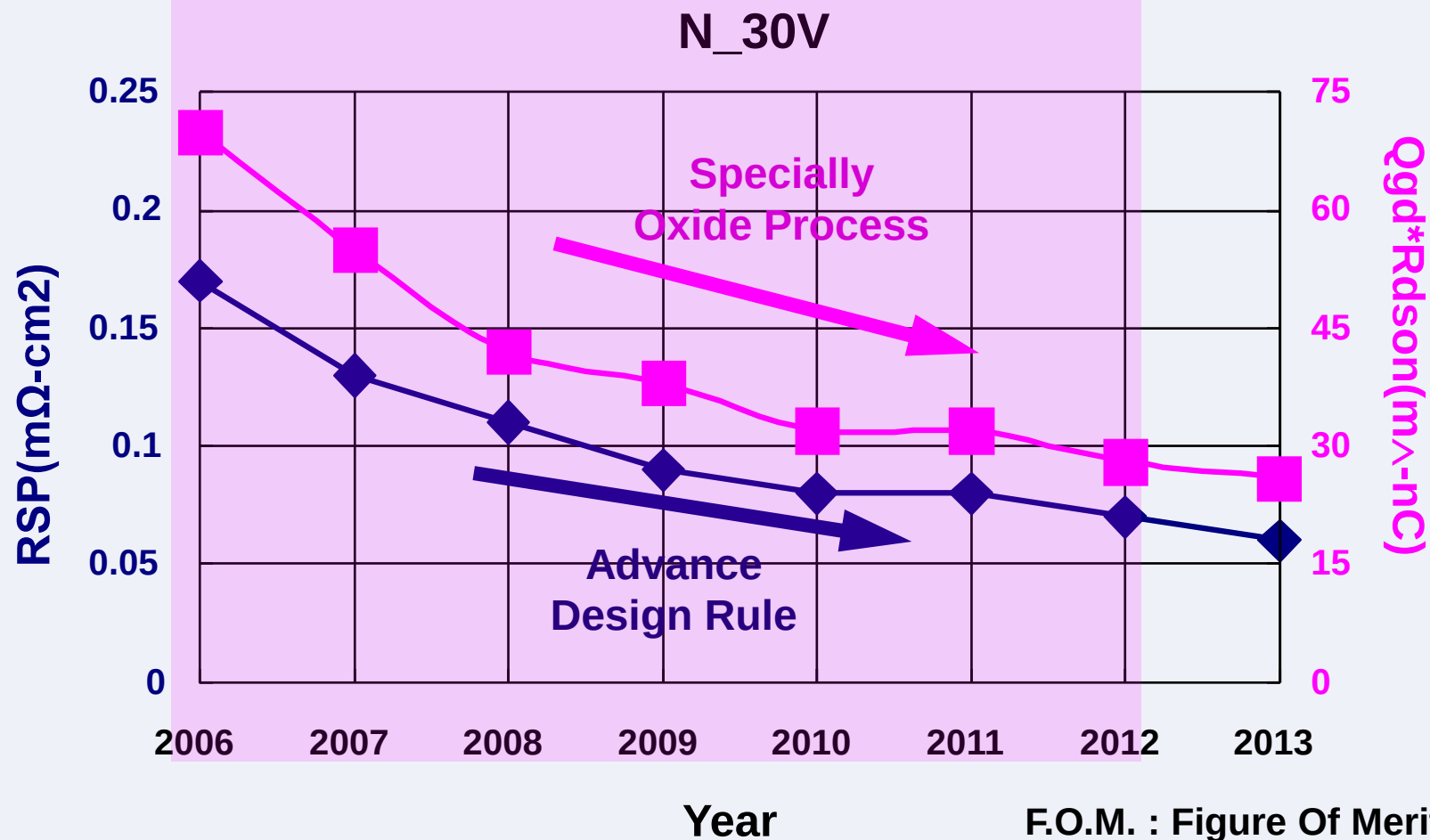


■ 20V-100V High Current 28%
 ■ 20V-100V Low Current 34%
 ■ 100V-400V 8%
 ■ 400V - 900V 30%

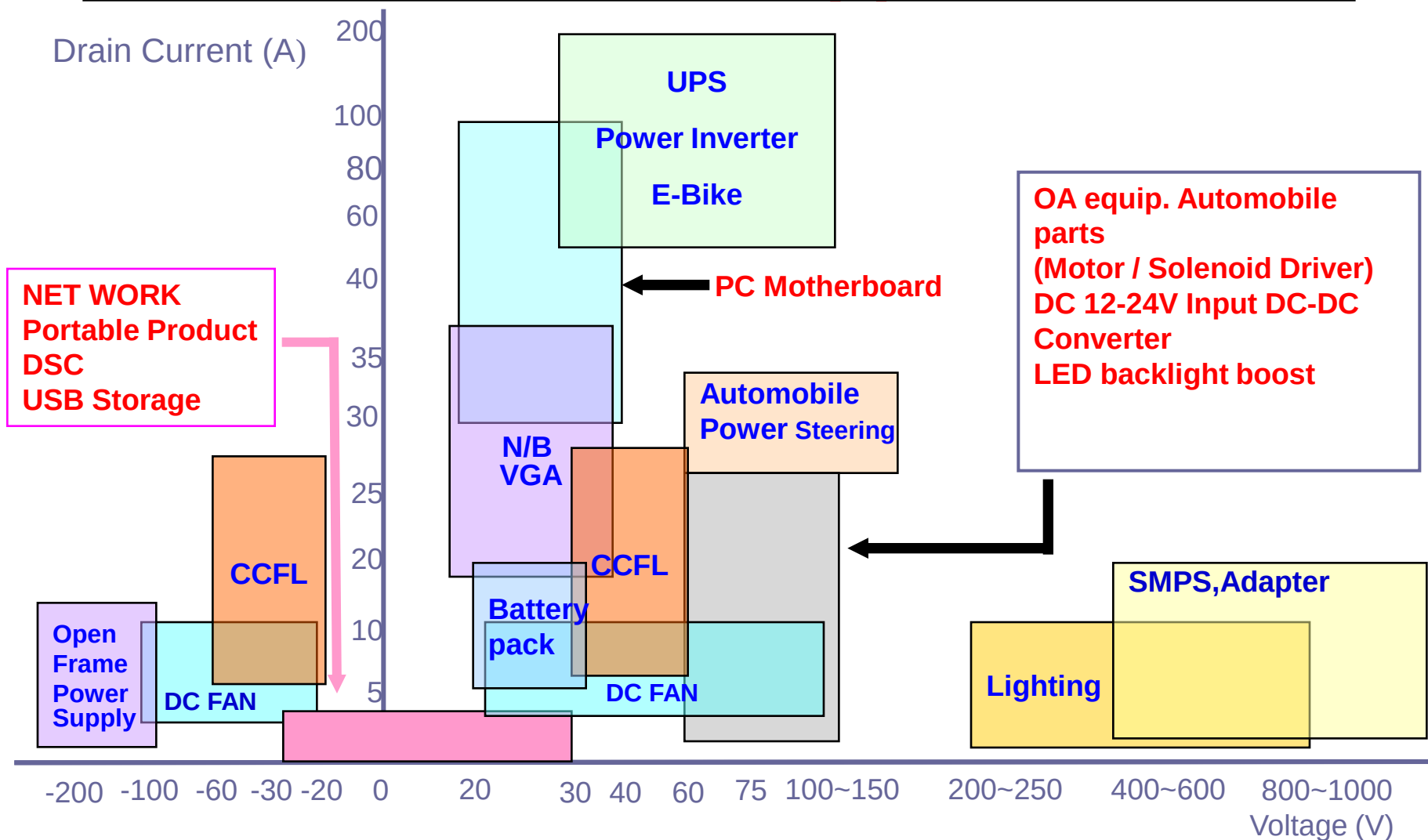
Technology Roadmap (F.O.M.)

CET

CET-MOS



Power Device Application



Global Support Spots



Why CET-MOS?

- **Inherit over 25 years experience from mother company. (Technology, Quality and Assembly)**
- **Broad variety of MOSFETs products and Plentiful package types.**
- **Complete R&D flow to meet customized request. (Market tap-in fast)**
- **Short Lead Time to add customer's competition.**

Thanks for Your Attention